

PMP9616 BOM			Rev B			
Count	RefDes	Part Number	Value	Description	MFR	Size
1	C5	GRM40yyyxxxKvv	0.068uF	Capacitor, Ceramic, 50V, X7R, [tol]	muRata	805
1	C4	GRM40yyyxxxKvv	0.1uF	Capacitor, Ceramic, vvV, [temp], [tol]	muRata	805
1	C6	GRM40yyyxxxKvv	1000pF	Capacitor, Ceramic, vvV, [temp], [tol]	muRata	805
1	C2	GRM40yyyxxxKvv	3300 pF	Capacitor, Ceramic, 50V, X7R, [tol]	muRata	805
2	C1	GRM40yyyxxxKvv	DNP	Capacitor, Ceramic, vvV, [temp], [tol]	muRata	805
	C3	GRM40yyyxxxKvv	DNP	Capacitor, Ceramic, vvV, [temp], [tol]	muRata	805
1	C15	C3225X7R1C226MT	22uF	Capacitor, Ceramic, 16V, X7R, 20%	TDK	1210
2	C7	ECA2AM221	2200uF	Capacitor, Aluminum Electrolytic, 2200uF, 100V	Panasonic	0.500 DIA
	C8	ECA2AM221	2200uF	Capacitor, Aluminum Electrolytic, 2200uF, 100V	Panasonic	0.500 DIA
2	C13	ECA2AM221	Open	Open	Panasonic	0.500 DIA
	C14	ECA2AM221	Open	Open	Panasonic	0.500 DIA
3	C9	Open	Open	Capacitor, Aluminum Electrolytic, 220uF, 100V	Panasonic	0.500 DIA
	C10	Open	Open	Capacitor, Aluminum Electrolytic, 220uF, 100V	Panasonic	0.500 DIA
	C11	Open	Open	Capacitor, Aluminum Electrolytic, 220uF, 100V	Panasonic	0.500 DIA
1	C12	Open	Open	Capacitor, Aluminum Electrolytic, xxV, ±20%, -40 to +85 °C	Panasonic	0.394 Dia.
6	J1	GSLU-70	{Value}	Lug, Solderless, #2 - #8 AWG, 1/4	Copper"	ILSCO
	J2	GSLU-70	{Value}	Lug, Solderless, #2 - #8 AWG, 1/4	Copper"	ILSCO
	J3	GSLU-70	{Value}	Lug, Solderless, #2 - #8 AWG, 1/4	Copper"	ILSCO
	J4	GSLU-70	{Value}	Lug, Solderless, #2 - #8 AWG, 1/4	Copper"	ILSCO
	J5	GSLU-70	{Value}	Lug, Solderless, #2 - #8 AWG, 1/4	Copper"	ILSCO
	J6	GSLU-70	{Value}	Lug, Solderless, #2 - #8 AWG, 1/4	Copper"	ILSCO
1	D3	BAS16	BAS16	Diode, Switching, 150-mA, 75-V, 350mW	Vishay-Liteon	SOT23
1	D1	B1xxB-13	B140	Diode, Schottky, 1A, xx-V	Diodes	SMA
1	D2	SMCJxxx[c]A-13-F	SMCJ14A	Diode, [Uni-]Directional TVS, 1500W, xx-A, yy-V	Diodes	SMC
1	J9	PTC36SAAN	PTC36SAAN	Header, Male 2-pin, 100mil spacing, (36-pin strip)	Sullins	0.100 inch x 2
1	R16	Std	0 OHM	Resistor, Chip, 1/10W, yy%	Std	805
3	R17	Std	1K	Resistor, Chip, 1/10W, yy%	Std	805
	R22	Std	1K	Resistor, Chip, 1/10W, yy%	Std	805
	R23	Std	1K	Resistor, Chip, 1/10W, yy%	Std	805

1	R19	Std	3K	Resistor, Chip, 1/10W, yy%	Std	805
1	R18	Std	8.2K	Resistor, Chip, 1/10W, yy%	Std	805
3	R6	Std	10	Resistor, Chip, 1/10W, yy%	Std	805
	R12	Std	10	Resistor, Chip, 1/10W, yy%	Std	805
	R14	Std	10	Resistor, Chip, 1/10W, yy%	Std	805
1	R8	Std	13.3K	Resistor, Chip, 1/10W, yy%	Std	805
1	R5	Std	20, 1%	Resistor, Chip, 1/10W, yy%	Std	805
1	R9	Std	191K	Resistor, Chip, 1/10W, yy%	Std	805
1	R7	Std	76.8K	Resistor, Chip, 1/10W, yy%	Std	805
1	R10	Std	22.6K	Resistor, Chip, 1/10W, yy%	Std	805
3	R11	Std	Open	Resistor, Chip, 1/10W, yy%	Std	805
	R13	Std	Open	Resistor, Chip, 1/10W, yy%	Std	805
	R15	Std	Open	Resistor, Chip, 1/10W, yy%	Std	805
2	R20	WSL-2512-xx 1% R86	510 OHM, 1W	Resistor, Chip, 1W, xx%	STD	2512
	R21	WSL-2512-xx 1% R86	510 OHM, 1W	Resistor, Chip, 1W, xx%	STD	2512
3	R2	WSL3637xx	0.003	Resistor, Power Metal Strip, x W, +/- yy%	Vishay Dale	3637
	R3	WSL3637xx	0.003	Resistor, Power Metal Strip, x W, +/- yy%	Vishay Dale	3637
	R4	WSL3637xx	0.003	Resistor, Power Metal Strip, x W, +/- yy%	Vishay Dale	3637
1	R1	Open	Open	Resistor, Power Metal Strip, x W, +/- yy%	Vishay Dale	3637
1	U1	SN2007031XDGS	TPS2490	IC, Positive High-Voltage Power Limiting Hotswap Controller	TI	VSSOP-10
1	S1	EG1213	EG1213	Switch, SPDT, Slide, PC-mount, RightAngle, 200-mA	E_Switch	0.394* 0.150 inch
2	J7	ED1514	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	OST	0.27 x 0.25 inch
	J8	ED1514	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	OST	0.27 x 0.25 inch
4	TP2	5011	5011	Test Point, Black, Thru Hole	Keystone	0.125 x 0.125 inch
	TP8	5011	5011	Test Point, Black, Thru Hole	Keystone	0.125 x 0.125 inch
	TP14	5011	5011	Test Point, Black, Thru Hole	Keystone	0.125 x 0.125 inch
	TP15	5011	5011	Test Point, Black, Thru Hole	Keystone	0.125 x 0.125 inch
11	TP1	5012	5012	Test Point, White, Thru Hole	Keystone	0.125 x 0.125 inch
	TP3	5012	5012	Test Point, White, Thru Hole	Keystone	0.125 x 0.125 inch
	TP4	5012	5012	Test Point, White, Thru Hole	Keystone	0.125 x 0.125 inch
	TP5	5012	5012	Test Point, White, Thru Hole	Keystone	0.125 x 0.125 inch
	TP6	5012	5012	Test Point, White, Thru Hole	Keystone	0.125 x 0.125 inch

	TP7	5012	5012	Test Point, White, Thru Hole	Keystone	0.125 x 0.125 inch
	TP9	5012	5012	Test Point, White, Thru Hole	Keystone	0.125 x 0.125 inch
	TP10	5012	5012	Test Point, White, Thru Hole	Keystone	0.125 x 0.125 inch
	TP11	5012	5012	Test Point, White, Thru Hole	Keystone	0.125 x 0.125 inch
	TP12	5012	5012	Test Point, White, Thru Hole	Keystone	0.125 x 0.125 inch
	TP13	5012	5012	Test Point, White, Thru Hole	Keystone	0.125 x 0.125 inch
1	Q6	2N7002DICT	2N7002	MOSFET, N-ch, 60-V, 115-mA, 1.2-Ohms	Vishay-Liteon	SOT23
2	Q2	CSD17570Q5B	CSD17570Q5B	MOSFET, N-Chan, 30V, 100A, 0.6milli-ohm	Ciclon	QFN-8 POWER
	Q4	CSD17570Q5B	CSD17570Q5B	MOSFET, N-Chan, 30V, 100A, 0.6milli-ohm	Ciclon	QFN-8 POWER
3	Q1	Open	Open	MOSFET, N-ch, 30-V, 30-A, 10.5 milliohm	IR	DPAK
	Q3	Open	Open	MOSFET, N-ch, 30-V, 30-A, 10.5 milliohm	IR	DPAK
	Q5	Open	Open	MOSFET, N-ch, 30-V, 30-A, 10.5 milliohm	IR	DPAK
1	Q7	PZT2907A	PZT2907A	Transistor, PNP, 60-V, 800-mA, 1000-mW	Fairchild	SOT-223

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